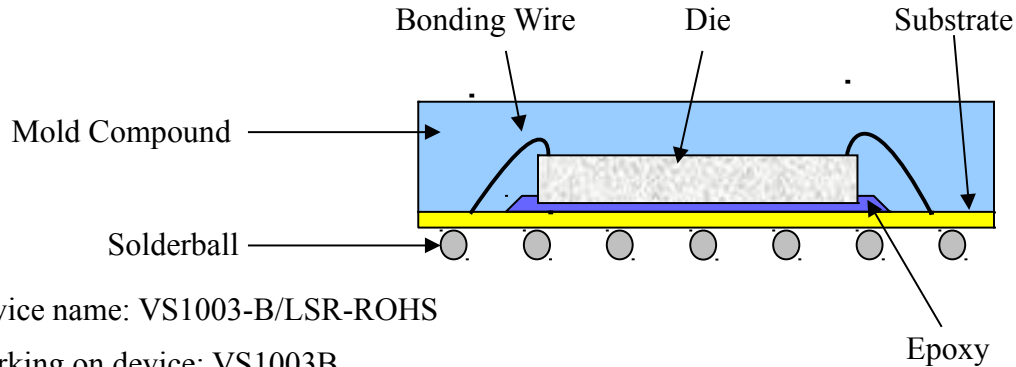


# Cross-Section View VS1003B 49pin FBGA (RoHS) Package



Device name: VS1003-B/LSR-ROHS

Marking on device: VS1003B

YYWW = assembly Year and Week  $\geq$  1346

## Substrate

plate composition: Cu, Au and Ni

plate thickness : Cu = 18 microns

Au = 0.3-1.0 microns

Ni = 5.0 microns minimum

**Total substrate thickness : 0.20 MM +/- 0.04 MM**

## Material

Solderball Sn 96.5%, Ag 3%, Cu 0.5%

Substrate HL832NX, AUS 308

Epoxy Die Attach ABLEBOND 2000B

Bonding Wire 25 um

Mold Compound EMEG760V